

BB02-BE :- 1.27mm X 1.27mm (0.05" X 0.05") BOX HEADER, THROUGH HOLE, DUAL ROW, STRAIGHT - 10 TO 100 CONTACTS

SPECIFICATIONS :

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 300 V
CONTACT RESISTANCE	20m OHMS MAX.
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	BRASS
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD : NYLON 6T
PLATING	GOLD, TIN, OR SELECTIVE OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC WAVE: 230°C FOR 5-10 SEC MANUAL SOLDER: 350°C FOR 3-5 SEC

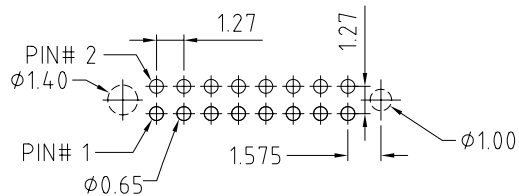
PACKED IN TRAY.

MATES WITH: BB02-CL BB02-CU  
BB02-CM  
BB02-CN  
BB02-CR

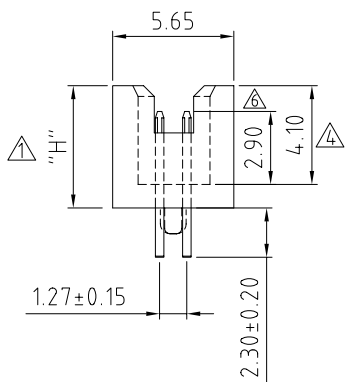
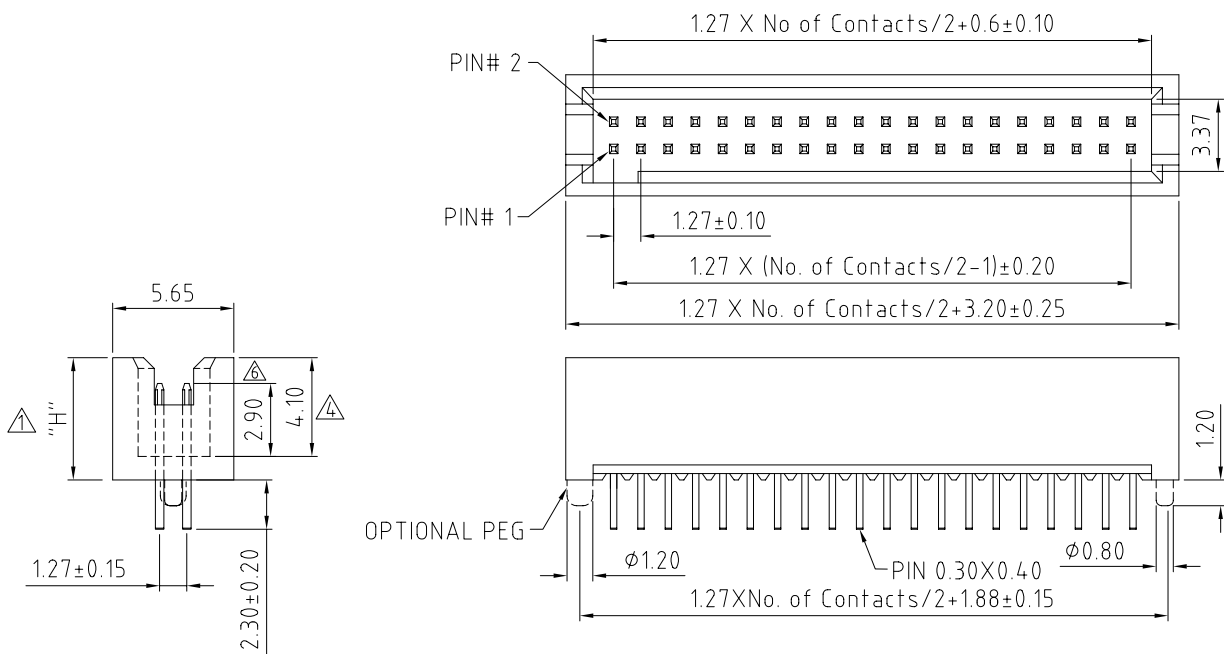
NOTES:

1. MATING HEIGHTS:

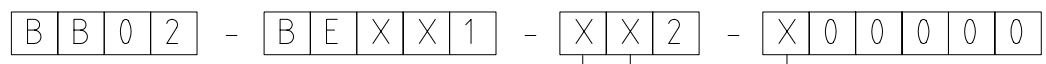
- a). WITH INSULATION HEIGHT OF A=5.7MM, THE MATING HEIGHT IS 1.6MM+SOCKET HEIGHT.
- b). WITH INSULATION HEIGHT OF B=7.3MM, THE MATING HEIGHT IS 3.2MM+SOCKET HEIGHT.



RECOMMENDED PC BOARD SMD LAYOUT  
(TOLERANCE: ±0.05)



HOW TO ORDER



NO. OF CONTACTS 10 TO 98 100 Contacts = 00	△ CONTACT PLATING OPTIONS K = GOLD FLASH (STANDARD) A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL T = BRIGHT TIN M = MATT TIN D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL E = 10U" GOLD ON CONTACT/BRIGHT TIN ON TAIL F = 15U" GOLD ON CONTACT/BRIGHT TIN ON TAIL G = 30U" GOLD ON CONTACT/BRIGHT TIN ON TAIL	△ "H" HEIGHT A = 5.70MM B = 7.30MM	WITH OR WITHOUT LOCATING PEG A = WITH B = WITHOUT
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REV.	DATE & DRN	10	19/09/05 - CHC RELEASE
		11	28/10/05 - NYW
		12	17/07/06 - NYW
		13	20/05/08 - CHC
		14	16/08/08 - NYW
		15	02/07/09 - CHC
		16	20/11/09 - NYW
		17	01/08/10 - NYW

Scale:	4:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 XXX ± 0.10	Material	SEE NOTE
Drawn:	CHC				
App'd:	NYW	Title	BOX HEADER		NOT TO SCALE
Date:	24 NOV '09	Revision:	16		UNIT: mm

		www.gradconn.com	
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Type:	BB02-BE
	BB02-BE
Drawing Number:	
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Drawing	© E and O E